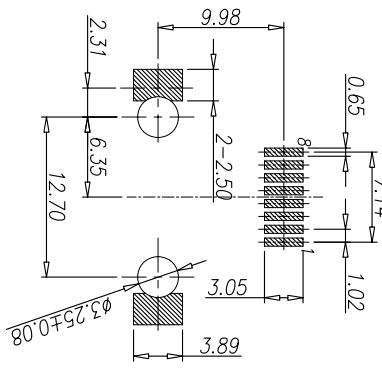
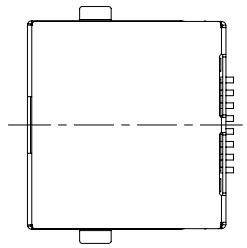


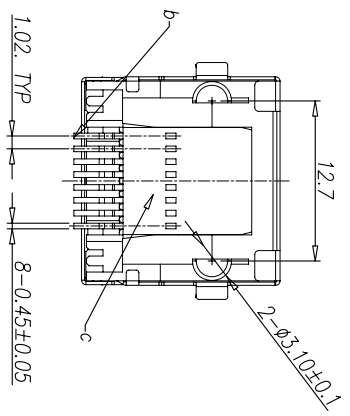
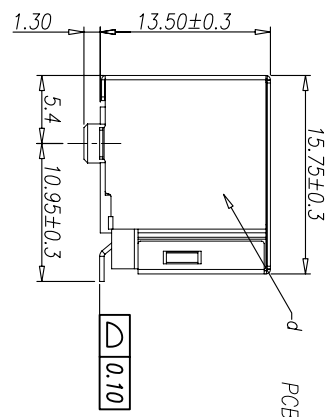
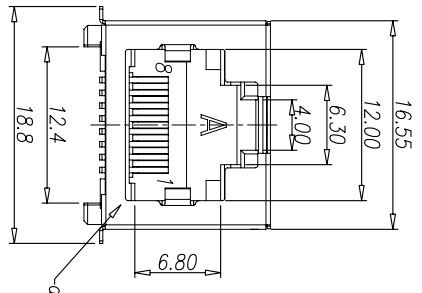
CATEGORY	DESCRIPTION	P/N #
CONNECTOR	Modular Jack, 8P8C, 90° WITH SHELL AND WITHOUT LED SMT TYPE	MJ5688-BX11-HR1-X

料号由原 MJ5688-BX11-HR1
变更为 MJ5688-BX11-HR1-X

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A01	—	New Release	XSY	2012.08.21
A02	—	整理图面, 修正管脚尺寸	XSY	2015.08.21
A03	—	新增包装选项	XSY	2016.05.06



RECOMMEND PCB LAYOUT
PCB THICKNESS: 1.60mm.
Jack Top View
PCB LAYOUT TOLERANCE: ± 0.05 mm.



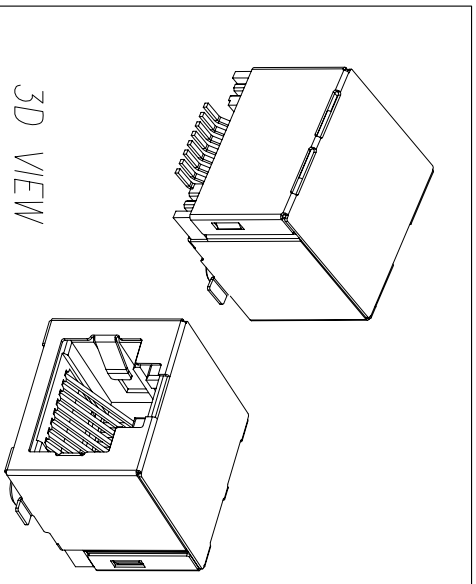
Material & Plating

X	Terminal Plating
0	Au 1u" Plating
1	Au 3u" Plating
2	Au 6u" Plating
3	Au 15u" Plating
4	Au 30u" Plating
5	Au 50u" Plating

X	包装方式
C	卷带包装
P	吸塑盒包装

d	Shell	1	Braze T=0.25mm	Plating Ni 30u" Min
c	Cover	1	LCP U194V-0	BLACK
b	Terminal	8	Phosphor Bronze T=0.35mm	Au/Tin Plating
a	Housing	1	LCP U194V-0	BLACK
NO.	PART NAME	QTY	MATERIAL	PLATING & COLOR

- Specifications:
1. Rated Current: 1.5A
 2. Contact resistance: 40mΩ MAX.
 3. Insulation resistance: 500MΩ MIN.
 4. Dielectric withstand: 500V AC for 1 minute
 5. Operating temperature: -40°C~+80°C
 6. Insertion/Extraction life: 750 Cycles
 7. To Conform to the "RoHS Directive"
 8. Resistance to reflow Soldering Heat 260°C 10 Seconds
 9. Solder ability Temperature 245±5°C, 5±0.5 Sec



东莞市合陵电子有限公司
DongGuan Heling Electronic Co.,LTD

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE: 1/1	UNIT: mm	DWG. NO:
DECIMALS: X ±0.5	SIZE: A3	PAGE: 1 OF 1	REV: A03
ANGLES: X ±2°	APPROVED BY	CHECKED BY	PREPARED BY
X.XX ±0.3	DICK	XSY	XSY
X.XXX ±0.2	CUSTOMER COPY		
X.XXX ±0.1	1		